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January 2008

# 74LVT244, 74LVTH244 Low Voltage Octal Buffer/Line Driver with 3-STATE Outputs

#### **Features**

- Input and output interface capability to systems at 5V V<sub>CC</sub>
- Bushold data inputs eliminate the need for external pull-up resistors to hold unused inputs (74LVTH244), also available without bushold feature (74LVT244)
- Live insertion/extraction permitted
- Power Up/Down high impedance provides glitch-free bus loading
- Outputs source/sink -32mA/+64mA
- Functionally compatible with the 74 series 244
- Latch-up performance exceeds 500mA
- ESD performance:
  - Human-body model > 2000V
  - Machine model > 200V
  - Charged-device model > 1000V

# **General Description**

The LVT244 and LVTH244 are octal buffers and line drivers designed to be employed as memory address drivers, clock drivers and bus oriented transmitters or receivers which provide improved PC board density.

The LVTH244 data inputs include bushold, eliminating the need for external pull-up resistors to hold unused inputs.

These octal buffers and line drivers are designed for low-voltage (3.3V)  $V_{CC}$  applications, but with the capability to provide a TTL interface to a 5V environment. The LVT244 and LVTH244 are fabricated with an advanced BiCMOS technology to achieve high speed operation similar to 5V ABT while maintaining low power dissipation.

# **Ordering Information**

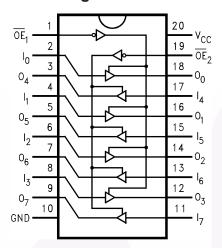
Order Number	Package Number	Package Description			
74LVT244WM	M20B	20-Lead Small Outline Integrated Circuit (SOIC), JEDEC MS-013, 0.300" Wide			
74LVT244SJ	M20D	20-Lead Small Outline Package (SOP), EIAJ TYPE II, 5.3mm Wide			
74LVT244MSA	MSA20	20-Lead Shrink Small Outline Package (SSOP), JEDEC MO-150, 5.3mm Wide			
74LVT244MTC	MTC20	20-Lead Thin Shrink Small Outline Package (TSSOP), JEDEC MO-153, 4.4mm Vide			
74LVTH244WM	M20B	0-Lead Small Outline Integrated Circuit (SOIC), JEDEC MS-013, 0.300" Wide			
74LVTH244SJ	M20D	0-Lead Small Outline Package (SOP), EIAJ TYPE II, 5.3mm Wide			
74LVTH244MSA	MSA20	20-Lead Shrink Small Outline Package (SSOP), JEDEC MO-150, 5.3mm Wide			
74LVTH244MTC	MTC20	20-Lead Thin Shrink Small Outline Package (TSSOP), JEDEC MO-153, 4.4mm Wide			

Device also available in Tape and Reel. Specify by appending suffix letter "X" to the ordering number.



All packages are lead free per JEDEC: J-STD-020B standard.

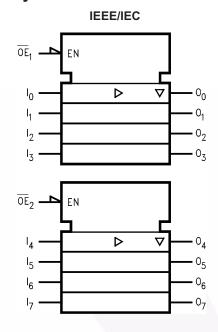
# **Connection Diagram**



# **Pin Description**

Pin Names	Description
$\overline{OE}_1$ , $\overline{OE}_2$	3-STATE Output Enable Inputs
I <sub>0</sub> –I <sub>7</sub>	Inputs
O <sub>0</sub> –O <sub>7</sub>	Output

# **Logic Symbol**



# **Truth Tables**

Inputs		Outputs
OE <sub>1</sub>	I <sub>n</sub>	(Pins 12, 14, 16, 18)
L	L	L
L	Н	Н
Н	Х	Z

Inp	uts	Outputs
OE <sub>2</sub>	In	(Pins 3, 5, 7, 9)
L	L	L
L	Н	Н
Н	Х	Z

H = HIGH Voltage Level

L = LOW Voltage Level

X = Immaterial

Z = High Impedance

# **Absolute Maximum Ratings**

Stresses exceeding the absolute maximum ratings may damage the device. The device may not function or be operable above the recommended operating conditions and stressing the parts to these levels is not recommended. In addition, extended exposure to stresses above the recommended operating conditions may affect device reliability. The absolute maximum ratings are stress ratings only.

Symbol	Parameter	Rating		
V <sub>CC</sub>	Supply Voltage	-0.5V to +4.6V		
V <sub>I</sub>	DC Input Voltage	-0.5V to +7.0V		
Vo	DC Output Voltage			
	Output in 3-STATE	-0.5V to +7.0V		
	Output in HIGH or LOW State <sup>(1)</sup>	-0.5V to +7.0V		
I <sub>IK</sub>	DC Input Diode Current, V <sub>1</sub> < GND			
I <sub>OK</sub>	DC Output Diode Current, V <sub>O</sub> < GND			
Io	DC Output Current, V <sub>O</sub> > V <sub>CC</sub>			
	Output at HIGH State	64mA		
	Output at LOW State	128mA		
I <sub>CC</sub>	DC Supply Current per Supply Pin	±64mA		
I <sub>GND</sub>	DC Ground Current per Ground Pin	±128mA		
T <sub>STG</sub>	Storage Temperature	−65°C to +150°C		

#### Note:

1. IO Absolute Maximum Rating must be observed.

# **Recommended Operating Conditions**

The Recommended Operating Conditions table defines the conditions for actual device operation. Recommended operating conditions are specified to ensure optimal performance to the datasheet specifications. Fairchild does not recommend exceeding them or designing to absolute maximum ratings.

Symbol	Parameter	Min	Max	Units
V <sub>CC</sub>	Supply Voltage	2.7	3.6	V
VI	Input Voltage	0	5.5	V
I <sub>OH</sub>	HIGH-Level Output Current		-32	mA
I <sub>OL</sub>	LOW-Level Output Current		64	mA
T <sub>A</sub>	Free-Air Operating Temperature	-40	85	°C
Δt / ΔV	Input Edge Rate, V <sub>IN</sub> = 0.8V–2.0V, V <sub>CC</sub> = 3.0V	0	10	ns/V

## **DC Electrical Characteristics**

					T A =	40°C to +	85°C	
Symbol Param		neter	V <sub>CC</sub> (V)	Conditions	Min.	Typ. <sup>(2)</sup>	Max.	Units
V <sub>IK</sub>	Input Clamp Di	iode Voltage	2.7	I <sub>I</sub> = -18mA			-1.2	V
V <sub>IH</sub>	Input HIGH Vo	ltage	2.7–3.6	$V_0 \le 0.1V$ or	2.0			V
V <sub>IL</sub>	Input LOW Voltage		2.7–3.6	$V_O \ge V_{CC} - 0.1V$			0.8	V
V <sub>OH</sub>	Output HIGH V	/oltage	2.7–3.6	$I_{OH} = -100 \mu A$	V <sub>CC</sub> -0.2			V
			2.7	$I_{OH} = -8mA$	2.4			
			3.0	$I_{OH} = -32mA$	2.0			
V <sub>OL</sub>	Output LOW V	oltage	2.7	$I_{OL} = 100 \mu A$			0.2	V
				I <sub>OL</sub> = 24mA			0.5	
			3.0	I <sub>OL</sub> = 16mA			0.4	
				$I_{OL} = 32mA$			0.5	
				$I_{OL} = 64 \text{mA}$			0.55	
I <sub>I(HOLD)</sub> (3)	Bushold Input	Minimum	3.0	V <sub>I</sub> = 0.8V	75			μA
,	Drive			V <sub>I</sub> = 2.0V	-75			1
I <sub>I(OD)</sub> <sup>(3)</sup>	Bushold Input	Over-Drive	3.0	(4)	500			μA
Current to Cha	nge State		(5)	-500				
I	Input Current		3.6	V <sub>I</sub> = 5.5V			10	μA
		Control Pins	3.6	$V_I = 0V \text{ or } V_{CC}$			±1	
		Data Pins	3.6	$V_I = 0V$			-5	
				$V_I = V_{CC}$			1	
I <sub>OFF</sub>	Power Off Leal	kage Current	0	$0V \le V_I \text{ or } V_O \le 5.5V$			±100	μA
I <sub>PU/PD</sub>	Power up/down Output Current		0–1.5V	$V_O = 0.5V$ to 3.0V, $V_I = GND$ or $V_{CC}$			±100	μA
I <sub>OZL</sub>	3-STATE Outpo	ut Leakage	3.6	V <sub>O</sub> = 0.5V			-5	μA
I <sub>OZH</sub>	3-STATE Output Current	ut Leakage	3.6	V <sub>O</sub> = 3.0V			5	μA
I <sub>OZH</sub> +	3-STATE Output Current	ut Leakage	3.6	$V_{CC} < V_O \le 5.5V$			10	μA
I <sub>CCH</sub>	Power Supply Current		3.6	Outputs HIGH			0.19	mA
I <sub>CCL</sub>	Power Supply Current		3.6	Outputs LOW			5	mA
I <sub>CCZ</sub>	Power Supply Current		3.6	Outputs Disabled			0.19	mA
I <sub>CCZ</sub> +	Power Supply Current		3.6	$V_{CC} \le V_O \le 5.5V$ , Outputs Disabled			0.19	mA
$\Delta I_{CC}$	Increase in Por Current <sup>(6)</sup>	wer Supply	3.6	One Input at V <sub>CC</sub> – 0.6V, Other Inputs at V <sub>CC</sub> or GND			0.2	mA

#### Notes:

- 2. All typical values are at  $V_{CC} = 3.3V$ ,  $T_A = 25^{\circ}C$ .
- 3. Applies to bushold versions only (74LVTH244).
- 4. An external driver must source at least the specified current to switch from LOW-to-HIGH.
- 5. An external driver must sink at least the specified current to switch from HIGH-to-LOW.
- 6. This is the increase in supply current for each input that is at the specified voltage level rather than  $V_{CC}$  or GND.

# Dynamic Switching Characteristics<sup>(7)</sup>

			Conditions	T <sub>A</sub> = 25°C		2	
Symbol	Parameter	V <sub>CC</sub> (V)	$C_L = 50 pF, R_L = 500 \Omega$	Min.	Тур.	Max.	Units
V <sub>OLP</sub>	Quiet Output Maximum Dynamic V <sub>OL</sub>	3.3	(8)		0.8		V
V <sub>OLV</sub>	Quiet Output Minimum Dynamic V <sub>OL</sub>	3.3	(8)		-0.8		V

## Notes:

- 7. Characterized in SOIC package. Guaranteed parameter, but not tested.
- 8. Max number of outputs defined as (n). n-1 data inputs are driven 0V to 3V. Output under test held LOW.

## **AC Electrical Characteristics**

				-40°C to + 50pF, R <sub>L</sub> =			
		V <sub>CC</sub>	= 3.3V ±	0.3V	V <sub>CC</sub> =	= 2.7V	
Symbol	Parameter	Min.	Typ. <sup>(9)</sup>	Max.	Min.	Max.	Units
t <sub>PLH</sub>	Propagation Delay, Data to Output	1.1		3.8	1.1	4.0	ns
t <sub>PHL</sub>		1.3		3.9	1.3	4.2	
t <sub>PZH</sub>	Output Enable Time	1.1		4.5	1.1	5.3	ns
t <sub>PZL</sub>		1.4		4.4	1.4	5.0	
t <sub>PHZ</sub>	Output Disable Time	1.9		4.9	1.9	5.1	ns
t <sub>PLZ</sub>		1.8		4.4	1.8	4.4	
toshl, toslh	Output to Output Skew <sup>(10)</sup>			1.0		1.0	ns

#### Notes:

- 9. All typical values are at  $V_{CC} = 3.3V$ ,  $T_A = 25$ °C.
- 10. Skew is defined as the absolute value of the difference between the actual propagation delay for any two separate outputs of the same device. The specification applies to any outputs switching in the same direction, either HIGH-to-LOW (t<sub>OSHL</sub>) or LOW-to-HIGH (t<sub>OSLH</sub>). Parameter guaranteed by design.

# Capacitance<sup>(11)</sup>

Symbol	Parameter	Conditions	Typical	Units
C <sub>IN</sub>	Input Capacitance	$V_{CC} = 0V$ , $V_I = 0V$ or $V_{CC}$	3	pF
C <sub>OUT</sub>	Output Capacitance	$V_{CC} = 3.0V$ , $V_{O} = 0V$ or $V_{CC}$	6	pF

## Note:

11. Capacitance is measured at frequency f = 1MHz, per MIL-STD-883, Method 3012.

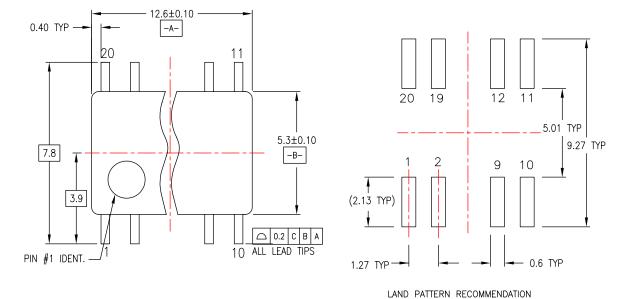
# **Physical Dimensions** 13.00 12.60 11.43 В 9.50 10.65 7.60 10.00 7.40 PIN ONE 0.35 INDICATOR **⊕** 0.25 **M** C B A LAND PATTERN RECOMMENDATION 2.65 MAX SEE DETAIL A 0.33 0.20 △ 0.10 C 0.30 0.10 0.75 SEATING PLANE NOTES: UNLESS OTHERWISE SPECIFIED (R0.10) A) THIS PACKAGE CONFORMS TO JEDEC GAGE PLANE MS-013, VARIATION AC, ISSUE E (R0.10) B) ALL DIMENSIONS ARE IN MILLIMETERS. 0.25 C) DIMENSIONS DO NOT INCLUDE MOLD FLASH OR BURRS. D) CONFORMS TO ASME Y14.5M-1994 0.40 SEATING PLANE E) LANDPATTERN STANDARD: SOIC127P1030X265-20L (1.40)DETAIL A F) DRAWING FILENAME: MKT-M20BREV3

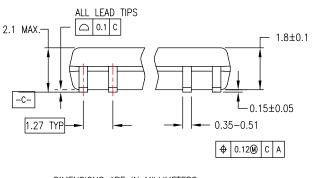
Figure 1. 20-Lead Small Outline Integrated Circuit (SOIC), JEDEC MS-013, 0.300" Wide

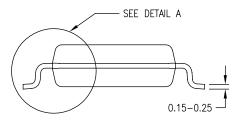
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# Physical Dimensions (Continued)





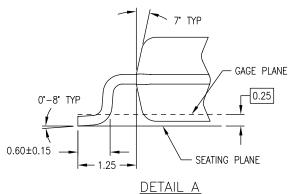


## DIMENSIONS ARE IN MILLIMETERS

# NOTES:

- A. CONFORMS TO EIAJ EDR-7320 REGISTRATION, ESTABLISHED IN DECEMBER, 1998.

  B. DIMENSIONS ARE IN MILLIMETERS.
  C. DIMENSIONS ARE EXCLUSIVE OF BURRS, MOLD FLASH, AND TIE BAR EXTRUSIONS.



M20DREVC

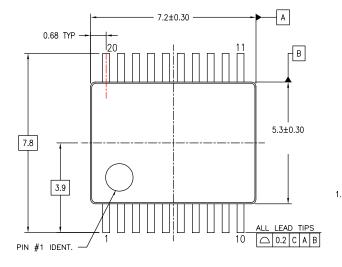
Figure 2. 20-Lead Small Outline Package (SOP), EIAJ TYPE II, 5.3mm Wide

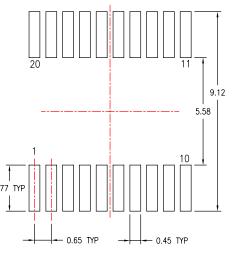
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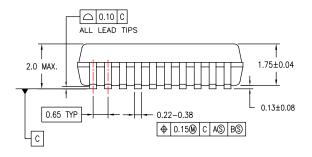
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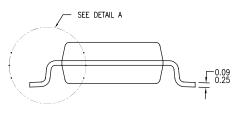
# Physical Dimensions (Continued)





LAND PATTERN RECOMMENDATIONS

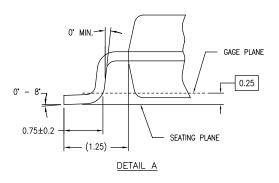




## DIMENSIONS ARE IN MILLIMETERS

#### NOTES:

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- B. DIMENSIONS ARE IN MILLIMETERS.
- C. DIMENSIONS ARE EXCLUSIVE OF BURRS, MOLD FLASH, AND TIE BAR EXTRUSIONS.
- D. DIMENSIONS AND TOLERANCES PER ASME Y14.5M 1994.



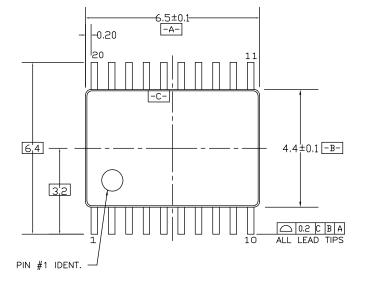
MSA20REVB

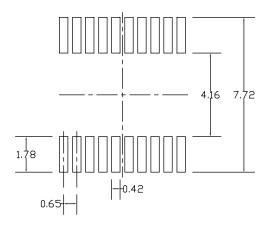
Figure 3. 20-Lead Shrink Small Outline Package (SSOP), JEDEC MO-150, 5.3mm Wide

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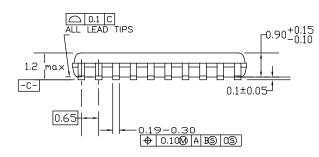
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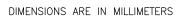
# Physical Dimensions (Continued)





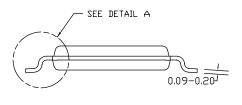
LAND PATTERN RECOMMENDATION

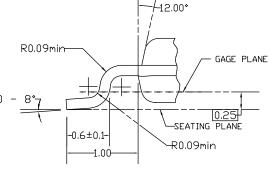




#### NOTES:

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- B. DIMENSIONS ARE IN MILLIMETERS.
- C. DIMENSIONS ARE EXCLUSIVE OF BURRS, MOLDS FLASH, AND TIE BAR EXTRUSIONS.
- D. DIMENSIONS AND TOLERANCES PER ANSI Y14.5M, 1982.





DETAIL A

## MTC20REVD1

## Figure 4. 20-Lead Thin Shrink Small Outline Package (TSSOP), JEDEC MO-153, 4.4mm Wide

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